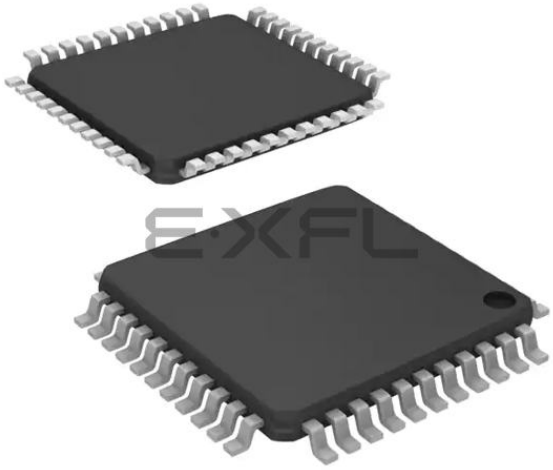

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Details	
Product Status	Active
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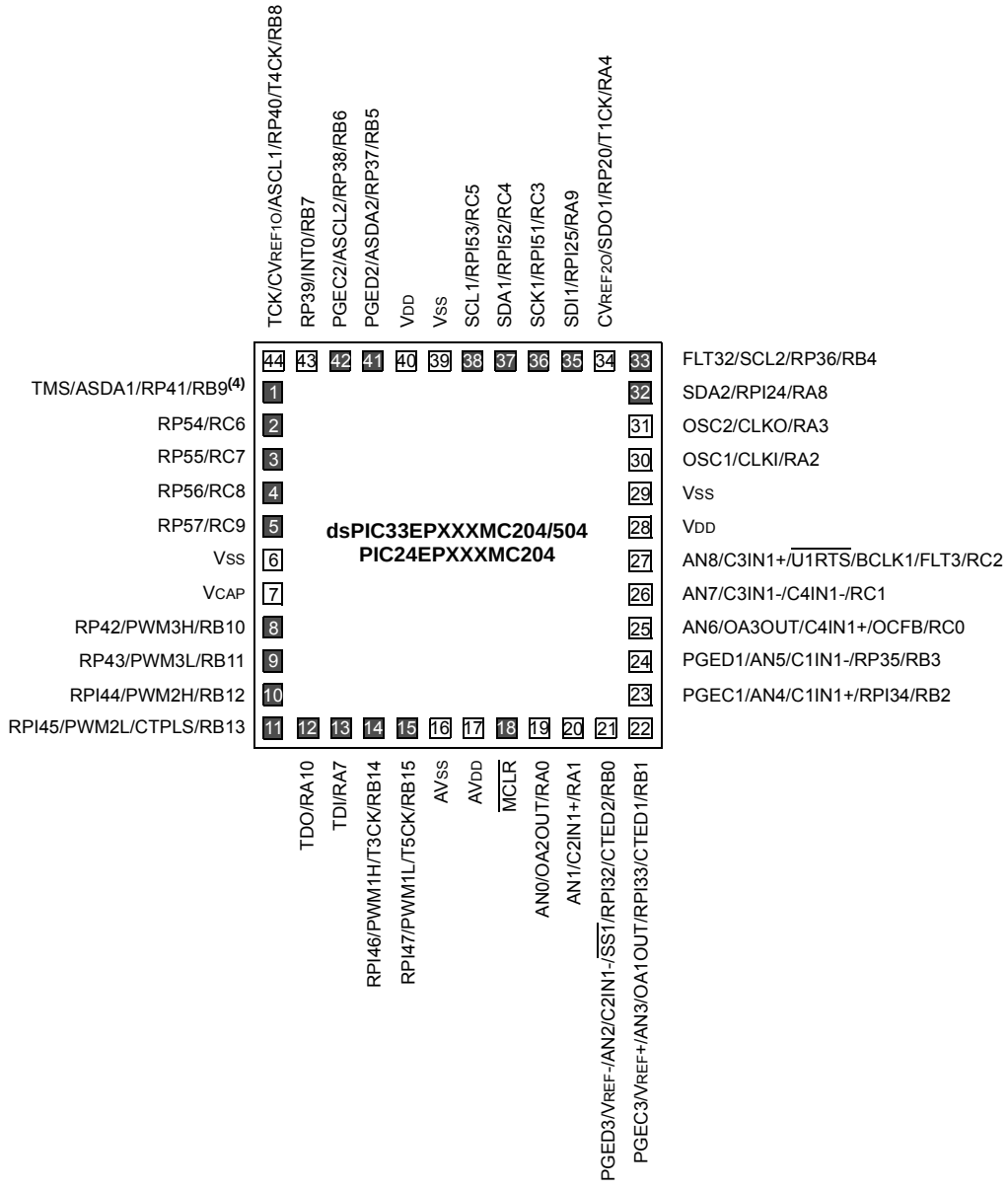
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	35
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep256gp204-e-pt

Pin Diagrams (Continued)

44-Pin VTLA(1,2,3)

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

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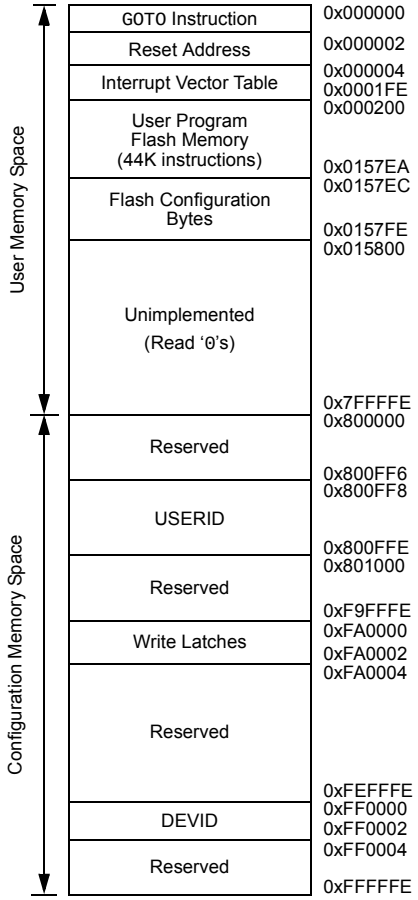
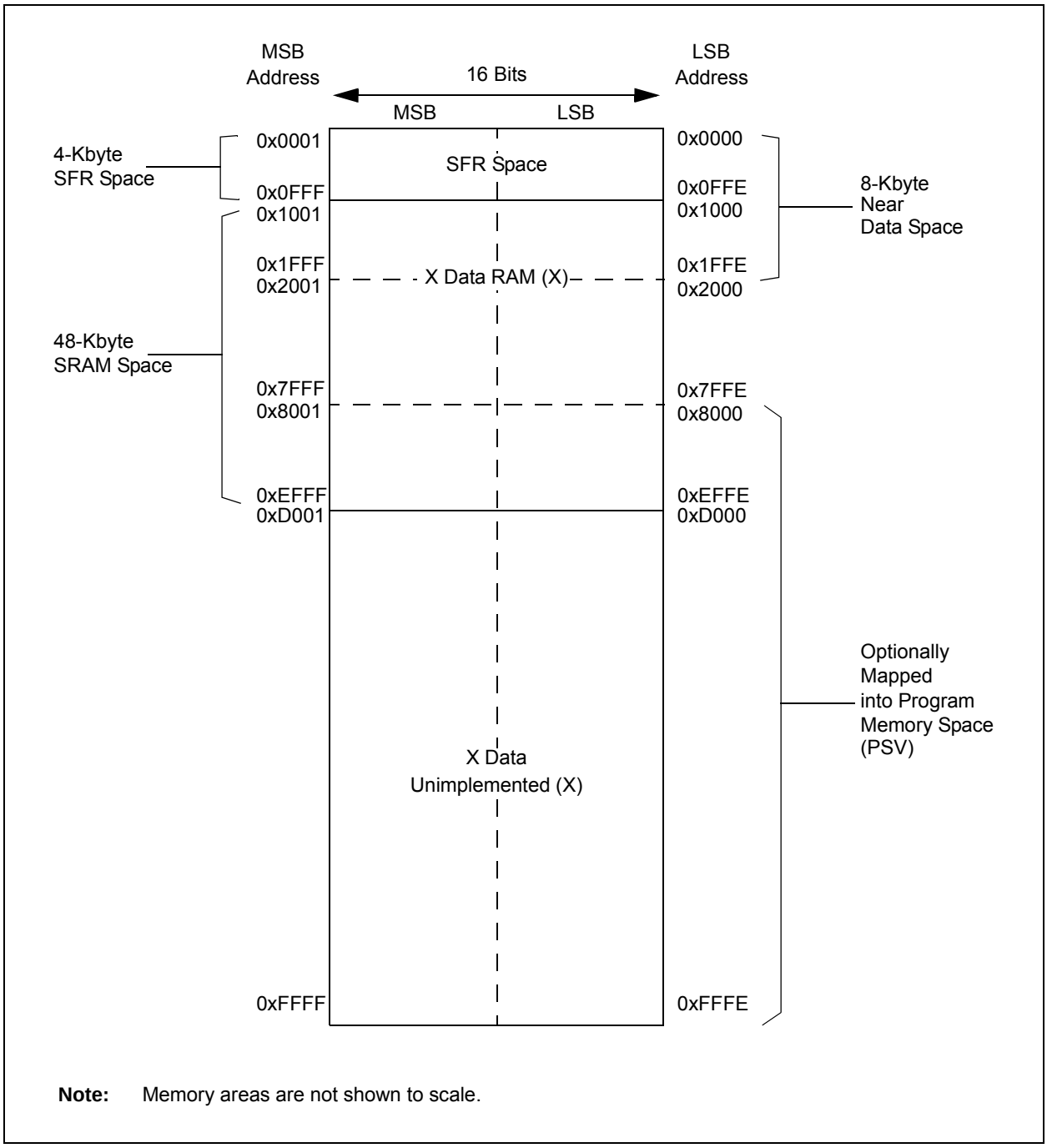
FIGURE 4-3: PROGRAM MEMORY MAP FOR dsPIC33EP128GP50X, dsPIC33EP128MC20X/50X AND PIC24EP128GP/MC20X DEVICES



Note: Memory areas are not shown to scale.

FIGURE 4-16: DATA MEMORY MAP FOR PIC24EP512GP/MC20X/50X DEVICES



Note: Memory areas are not shown to scale.

TABLE 4-21: ECAN1 REGISTER MAP WHEN WIN (C1CTRL1<0>) = 0 OR 1 FOR dsPIC33EPXXXMC/GP50X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
C1CTRL1	0400	—	—	CSIDL	ABAT	CANCKS	REQOP<2:0>			OPMODE<2:0>			—	CANCAP	—	—	WIN	0480
C1CTRL2	0402	—	—	—	—	—	—	—	—	—	—	—	DNCNT<4:0>					0000
C1VEC	0404	—	—	—	FILHIT<4:0>					—	ICODE<6:0>							0040
C1FCTRL	0406	DMABS<2:0>			—	—	—	—	—	—	—	—	FSA<4:0>					0000
C1FIFO	0408	—	—	FBP<5:0>						—	—	FNRB<5:0>						0000
C1INTF	040A	—	—	TXBO	TXBP	RXBP	TXWAR	RXWAR	EWARN	IVRIF	WAKIF	ERRIF	—	FIFOIF	RBOVIF	RBIF	TBIF	0000
C1INTE	040C	—	—	—	—	—	—	—	—	IVRIE	WAKIE	ERRIE	—	FIFOIE	RBOVIE	RBIE	TBIE	0000
C1EC	040E	TERRCNT<7:0>								RERRCNT<7:0>								0000
C1CFG1	0410	—	—	—	—	—	—	—	—	SJW<1:0>		BRP<5:0>						0000
C1CFG2	0412	—	WAKFIL	—	—	—	SEG2PH<2:0>			SEG2PHTS	SAM	SEG1PH<2:0>			PRSEG<2:0>			0000
C1FEN1	0414	FLTEN15	FLTEN14	FLTEN13	FLTEN12	FLTEN11	FLTEN10	FLTEN9	FLTEN8	FLTEN7	FLTEN6	FLTEN5	FLTEN4	FLTEN3	FLTEN2	FLTEN1	FLTEN0	FFFF
C1FMSKSEL1	0418	F7MSK<1:0>		F6MSK<1:0>		F5MSK<1:0>		F4MSK<1:0>		F3MSK<1:0>		F2MSK<1:0>		F1MSK<1:0>		F0MSK<1:0>		0000
C1FMSKSEL2	041A	F15MSK<1:0>		F14MSK<1:0>		F13MSK<1:0>		F12MSK<1:0>		F11MSK<1:0>		F10MSK<1:0>		F9MSK<1:0>		F8MSK<1:0>		0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-22: ECAN1 REGISTER MAP WHEN WIN (C1CTRL1<0>) = 0 FOR dsPIC33EPXXXMC/GP50X DEVICES ONLY

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
	0400-041E	See definition when WIN = x																
C1RXFUL1	0420	RXFUL15	RXFUL14	RXFUL13	RXFUL12	RXFUL11	RXFUL10	RXFUL9	RXFUL8	RXFUL7	RXFUL6	RXFUL5	RXFUL4	RXFUL3	RXFUL2	RXFUL1	RXFUL0	0000
C1RXFUL2	0422	RXFUL31	RXFUL30	RXFUL29	RXFUL28	RXFUL27	RXFUL26	RXFUL25	RXFUL24	RXFUL23	RXFUL22	RXFUL21	RXFUL20	RXFUL19	RXFUL18	RXFUL17	RXFUL16	0000
C1RXOVF1	0428	RXOVF15	RXOVF14	RXOVF13	RXOVF12	RXOVF11	RXOVF10	RXOVF9	RXOVF8	RXOVF7	RXOVF6	RXOVF5	RXOVF4	RXOVF3	RXOVF2	RXOVF1	RXOVF0	0000
C1RXOVF2	042A	RXOVF31	RXOVF30	RXOVF29	RXOVF28	RXOVF27	RXOVF26	RXOVF25	RXOVF24	RXOVF23	RXOVF22	RXOVF21	RXOVF20	RXOVF19	RXOVF18	RXOVF17	RXOVF16	0000
C1TR01CON	0430	TXEN1	TXABT1	TXLARB1	TXERR1	TXREQ1	RTREN1	TX1PRI<1:0>		TXEN0	TXABAT0	TXLARB0	TXERR0	TXREQ0	RTREN0	TX0PRI<1:0>		0000
C1TR23CON	0432	TXEN3	TXABT3	TXLARB3	TXERR3	TXREQ3	RTREN3	TX3PRI<1:0>		TXEN2	TXABAT2	TXLARB2	TXERR2	TXREQ2	RTREN2	TX2PRI<1:0>		0000
C1TR45CON	0434	TXEN5	TXABT5	TXLARB5	TXERR5	TXREQ5	RTREN5	TX5PRI<1:0>		TXEN4	TXABAT4	TXLARB4	TXERR4	TXREQ4	RTREN4	TX4PRI<1:0>		0000
C1TR67CON	0436	TXEN7	TXABT7	TXLARB7	TXERR7	TXREQ7	RTREN7	TX7PRI<1:0>		TXEN6	TXABAT6	TXLARB6	TXERR6	TXREQ6	RTREN6	TX6PRI<1:0>		xxxx
C1RXD	0440	ECAN1 Receive Data Word																xxxx
C1TXD	0442	ECAN1 Transmit Data Word																xxxx

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

FIGURE 4-21: BIT-REVERSED ADDRESSING EXAMPLE

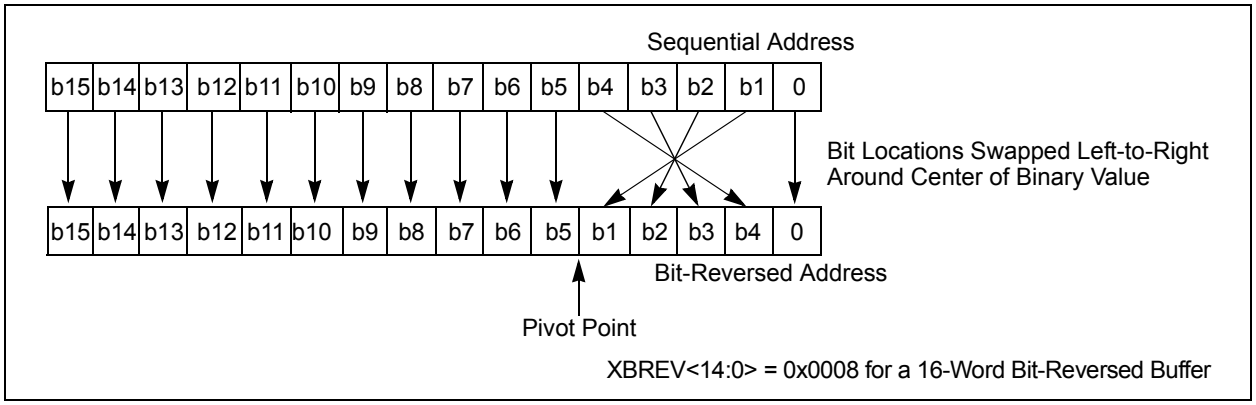


TABLE 4-64: BIT-REVERSED ADDRESSING SEQUENCE (16-ENTRY)

Normal Address					Bit-Reversed Address				
A3	**A2**	**A1**	**A0**	**Decimal**	**A3**	**A2**	**A1**	**A0**	**Decimal**
0	0	0	0	0	0	0	0	0	0
0	0	0	1	1	1	0	0	0	8
0	0	1	0	2	0	1	0	0	4
0	0	1	1	3	1	1	0	0	12
0	1	0	0	4	0	0	1	0	2
0	1	0	1	5	1	0	1	0	10
0	1	1	0	6	0	1	1	0	6
0	1	1	1	7	1	1	1	0	14
1	0	0	0	8	0	0	0	1	1
1	0	0	1	9	1	0	0	1	9
1	0	1	0	10	0	1	0	1	5
1	0	1	1	11	1	1	0	1	13
1	1	0	0	12	0	0	1	1	3
1	1	0	1	13	1	0	1	1	11
1	1	1	0	14	0	1	1	1	7
1	1	1	1	15	1	1	1	1	15

REGISTER 10-1: PMD1: PERIPHERAL MODULE DISABLE CONTROL REGISTER 1 (CONTINUED)

bit 3 **SPI1MD:** SPI1 Module Disable bit
1 = SPI1 module is disabled
0 = SPI1 module is enabled

bit 2 **Unimplemented:** Read as '0'

bit 1 **C1MD:** ECAN1 Module Disable bit(2)
1 = ECAN1 module is disabled
0 = ECAN1 module is enabled

bit 0 **AD1MD:** ADC1 Module Disable bit
1 = ADC1 module is disabled
0 = ADC1 module is enabled

Note 1: This bit is available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.
2: This bit is available on dsPIC33EPXXXGP50X and dsPIC33EPXXXMC50X devices only.

13.2 Timer Control Registers

REGISTER 13-1: TxCON: (TIMER2 AND TIMER4) CONTROL REGISTER

R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
TON	—	TSIDL	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	U-0
—	TGATE	TCKPS1	TCKPS0	T32	—	TCS	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **TON:** Timerx On bit
When T32 = 1:
1 = Starts 32-bit Timerx/y
0 = Stops 32-bit Timerx/y
When T32 = 0:
1 = Starts 16-bit Timerx
0 = Stops 16-bit Timerx

bit 14 **Unimplemented:** Read as '0'

bit 13 **TSIDL:** Timerx Stop in Idle Mode bit
1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12-7 **Unimplemented:** Read as '0'

bit 6 **TGATE:** Timerx Gated Time Accumulation Enable bit
When TCS = 1:
This bit is ignored.
When TCS = 0:
1 = Gated time accumulation is enabled
0 = Gated time accumulation is disabled

bit 5-4 **TCKPS<1:0>:** Timerx Input Clock Prescale Select bits
11 = 1:256
10 = 1:64
01 = 1:8
00 = 1:1

bit 3 **T32:** 32-Bit Timer Mode Select bit
1 = Timerx and Timery form a single 32-bit timer
0 = Timerx and Timery act as two 16-bit timers

bit 2 **Unimplemented:** Read as '0'

bit 1 **TCS:** Timerx Clock Source Select bit
1 = External clock is from pin, TxCK (on the rising edge)
0 = Internal clock (FP)

bit 0 **Unimplemented:** Read as '0'

18.1 SPI Helpful Tips

1. In Frame mode, if there is a possibility that the master may not be initialized before the slave:
   a) If FRMPOL (SPIxCON2<13>) = 1, use a pull-down resistor on SSx.
   b) If FRMPOL = 0, use a pull-up resistor on SSx.

Note:	This insures that the first frame transmission after initialization is not shifted or corrupted.

2. In Non-Framed 3-Wire mode, (i.e., not using SSx from a master):
   a) If CKP (SPIxCON1<6>) = 1, always place a pull-up resistor on SSx.
   b) If CKP = 0, always place a pull-down resistor on SSx.

Note:	This will insure that during power-up and initialization the master/slave will not lose Sync due to an errant SCKx transition that would cause the slave to accumulate data shift errors for both transmit and receive appearing as corrupted data.

3. FRMEN (SPIxCON2<15>) = 1 and SSEN (SPIxCON1<7>) = 1 are exclusive and invalid. In Frame mode, SCKx is continuous and the Frame Sync pulse is active on the SSx pin, which indicates the start of a data frame.

Note:	Not all third-party devices support Frame mode timing. Refer to the SPIx specifications in **Section 30.0 "Electrical Characteristics"** for details.

4. In Master mode only, set the SMP bit (SPIxCON1<9>) to a '1' for the fastest SPIx data rate possible. The SMP bit can only be set at the same time or after the MSTEN bit (SPIxCON1<5>) is set.

To avoid invalid slave read data to the master, the user's master software must ensure enough time for slave software to fill its write buffer before the user application initiates a master write/read cycle. It is always advisable to preload the SPIxBUF Transmit register in advance of the next master transaction cycle. SPIxBUF is transferred to the SPIx Shift register and is empty once the data transmission begins.

18.2 SPI Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

18.2.1 KEY RESOURCES

- **"Serial Peripheral Interface (SPI)"** (DS70569) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

21.2 Modes of Operation

The ECAN module can operate in one of several operation modes selected by the user. These modes include:

- Initialization mode
- Disable mode
- Normal Operation mode
- Listen Only mode
- Listen All Messages mode
- Loopback mode

Modes are requested by setting the REQOP<2:0> bits (CxCTRL1<10:8>). Entry into a mode is Acknowledged by monitoring the OPMODE<2:0> bits (CxCTRL1<7:5>). The module does not change the mode and the OPMODEx bits until a change in mode is acceptable, generally during bus Idle time, which is defined as at least 11 consecutive recessive bits.

21.3 ECAN Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

21.3.1 KEY RESOURCES

- **"Enhanced Controller Area Network (ECAN™)"** (DS70353) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

REGISTER 23-4: AD1CON4: ADC1 CONTROL REGISTER 4

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	ADDMAEN
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	DMABL2	DMABL1	DMABL0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as ‘0’

bit 8 **ADDMAEN:** ADC1 DMA Enable bit

1 = Conversion results are stored in the ADC1BUF0 register for transfer to RAM using DMA
0 = Conversion results are stored in ADC1BUF0 through ADC1BUFF registers; DMA will not be used

bit 7-3 **Unimplemented:** Read as ‘0’

bit 2-0 **DMABL<2:0>:** Selects Number of DMA Buffer Locations per Analog Input bits

111 = Allocates 128 words of buffer to each analog input
110 = Allocates 64 words of buffer to each analog input
101 = Allocates 32 words of buffer to each analog input
100 = Allocates 16 words of buffer to each analog input
011 = Allocates 8 words of buffer to each analog input
010 = Allocates 4 words of buffer to each analog input
001 = Allocates 2 words of buffer to each analog input
000 = Allocates 1 word of buffer to each analog input

REGISTER 26-3: CRCXORH: CRC XOR POLYNOMIAL HIGH REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
X<31:24>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
X<23:16>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **X<31:16>:** XOR of Polynomial Term X^n Enable bits

REGISTER 26-4: CRCXORL: CRC XOR POLYNOMIAL LOW REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
X<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0
X<7:1>							—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-1 **X<15:1>:** XOR of Polynomial Term X^n Enable bits

bit 0 **Unimplemented:** Read as ‘0’

NOTES:

TABLE 27-2: CONFIGURATION BITS DESCRIPTION

Bit Field	Description
GCP	General Segment Code-Protect bit 1 = User program memory is not code-protected 0 = Code protection is enabled for the entire program memory space
GWRP	General Segment Write-Protect bit 1 = User program memory is not write-protected 0 = User program memory is write-protected
IESO	Two-Speed Oscillator Start-up Enable bit 1 = Start up device with FRC, then automatically switch to the user-selected oscillator source when ready 0 = Start up device with user-selected oscillator source
PWMLOCK(1)	PWM Lock Enable bit 1 = Certain PWM registers may only be written after a key sequence 0 = PWM registers may be written without a key sequence
FNOSC<2:0>	Oscillator Selection bits 111 = Fast RC Oscillator with Divide-by-N (FRCDIVN) 110 = Fast RC Oscillator with Divide-by-16 (FRCDIV16) 101 = Low-Power RC Oscillator (LPRC) 100 = Reserved; do not use 011 = Primary Oscillator with PLL module (XT + PLL, HS + PLL, EC + PLL) 010 = Primary Oscillator (XT, HS, EC) 001 = Fast RC Oscillator with Divide-by-N with PLL module (FRCPLL) 000 = Fast RC Oscillator (FRC)
FCKSM<1:0>	Clock Switching Mode bits 1x = Clock switching is disabled, Fail-Safe Clock Monitor is disabled 01 = Clock switching is enabled, Fail-Safe Clock Monitor is disabled 00 = Clock switching is enabled, Fail-Safe Clock Monitor is enabled
IOL1WAY	Peripheral Pin Select Configuration bit 1 = Allow only one reconfiguration 0 = Allow multiple reconfigurations
OSCIOFNC	OSC2 Pin Function bit (except in XT and HS modes) 1 = OSC2 is the clock output 0 = OSC2 is a general purpose digital I/O pin
POSCMD<1:0>	Primary Oscillator Mode Select bits 11 = Primary Oscillator is disabled 10 = HS Crystal Oscillator mode 01 = XT Crystal Oscillator mode 00 = EC (External Clock) mode
FWDTEN	Watchdog Timer Enable bit 1 = Watchdog Timer is always enabled (LPRC oscillator cannot be disabled. Clearing the SWDTEN bit in the RCON register will have no effect.) 0 = Watchdog Timer is enabled/disabled by user software (LPRC can be disabled by clearing the SWDTEN bit in the RCON register)
WINDIS	Watchdog Timer Window Enable bit 1 = Watchdog Timer in Non-Window mode 0 = Watchdog Timer in Window mode
PLLKEN	PLL Lock Enable bit 1 = PLL lock is enabled 0 = PLL lock is disabled

Note 1: This bit is only available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices.

2: When JTAGEN = 1, an internal pull-up resistor is enabled on the TMS pin. Erased devices default to JTAGEN = 1. Applications requiring I/O pins in a high-impedance state (tri-state) in Reset should use pins other than TMS for this purpose.

27.5 Watchdog Timer (WDT)

For dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices, the WDT is driven by the LPRC oscillator. When the WDT is enabled, the clock source is also enabled.

27.5.1 PRESCALER/POSTSCALER

The nominal WDT clock source from LPRC is 32 kHz. This feeds a prescaler that can be configured for either 5-bit (divide-by-32) or 7-bit (divide-by-128) operation. The prescaler is set by the WDTPRE Configuration bit. With a 32 kHz input, the prescaler yields a WDT Time-out period (TWDT), as shown in Parameter SY12 in Table 30-22.

A variable postscaler divides down the WDT prescaler output and allows for a wide range of time-out periods. The postscaler is controlled by the WDTPOST<3:0> Configuration bits (FWDT<3:0>), which allow the selection of 16 settings, from 1:1 to 1:32,768. Using the prescaler and postscaler, time-out periods ranging from 1 ms to 131 seconds can be achieved.

The WDT, prescaler and postscaler are reset:

- On any device Reset
- On the completion of a clock switch, whether invoked by software (i.e., setting the OSWEN bit after changing the NOSCx bits) or by hardware (i.e., Fail-Safe Clock Monitor)
- When a PWRSAV instruction is executed (i.e., Sleep or Idle mode is entered)
- When the device exits Sleep or Idle mode to resume normal operation
- By a CLRWDT instruction during normal execution

Note: The CLRWDT and PWRSAV instructions clear the prescaler and postscaler counts when executed.

27.5.2 SLEEP AND IDLE MODES

If the WDT is enabled, it continues to run during Sleep or Idle modes. When the WDT time-out occurs, the device wakes the device and code execution continues from where the PWRSAV instruction was executed. The corresponding SLEEP or IDLE bit (RCON<3,2>) needs to be cleared in software after the device wakes up.

27.5.3 ENABLING WDT

The WDT is enabled or disabled by the FWDTEN Configuration bit in the FWDT Configuration register. When the FWDTEN Configuration bit is set, the WDT is always enabled.

The WDT can be optionally controlled in software when the FWDTEN Configuration bit has been programmed to '0'. The WDT is enabled in software by setting the SWDTEN control bit (RCON<5>). The SWDTEN control bit is cleared on any device Reset. The software WDT option allows the user application to enable the WDT for critical code segments and disable the WDT during non-critical segments for maximum power savings.

The WDT flag bit, WDTO (RCON<4>), is not automatically cleared following a WDT time-out. To detect subsequent WDT events, the flag must be cleared in software.

27.5.4 WDT WINDOW

The Watchdog Timer has an optional Windowed mode, enabled by programming the WINDIS bit in the WDT Configuration register (FWDT<6>). In the Windowed mode (WINDIS = 0), the WDT should be cleared based on the settings in the programmable Watchdog Timer Window select bits (WDTWIN<1:0>).

FIGURE 27-2: WDT BLOCK DIAGRAM

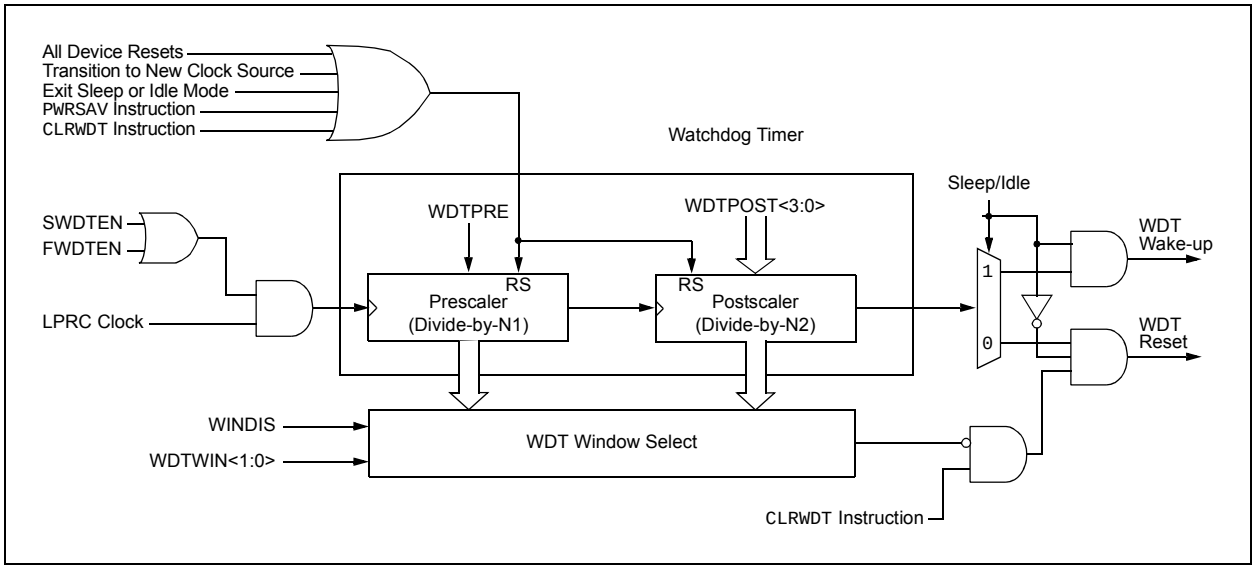


TABLE 30-9: DC CHARACTERISTICS: WATCHDOG TIMER DELTA CURRENT (ΔI_{WDT})(1)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended		
Parameter No.	**Typ.**	**Max.**	**Units**	**Conditions**	
DC61d	8	—	μA	-40°C	3.3V
DC61a	10	—	μA	+25°C	
DC61b	12	—	μA	+85°C	
DC61c	13	—	μA	+125°C	

Note 1: The ΔI_{WDT} current is the additional current consumed when the module is enabled. This current should be added to the base I_{PD} current. All parameters are characterized but not tested during manufacturing.

TABLE 30-10: DC CHARACTERISTICS: DOZE CURRENT (I_{DOZE})

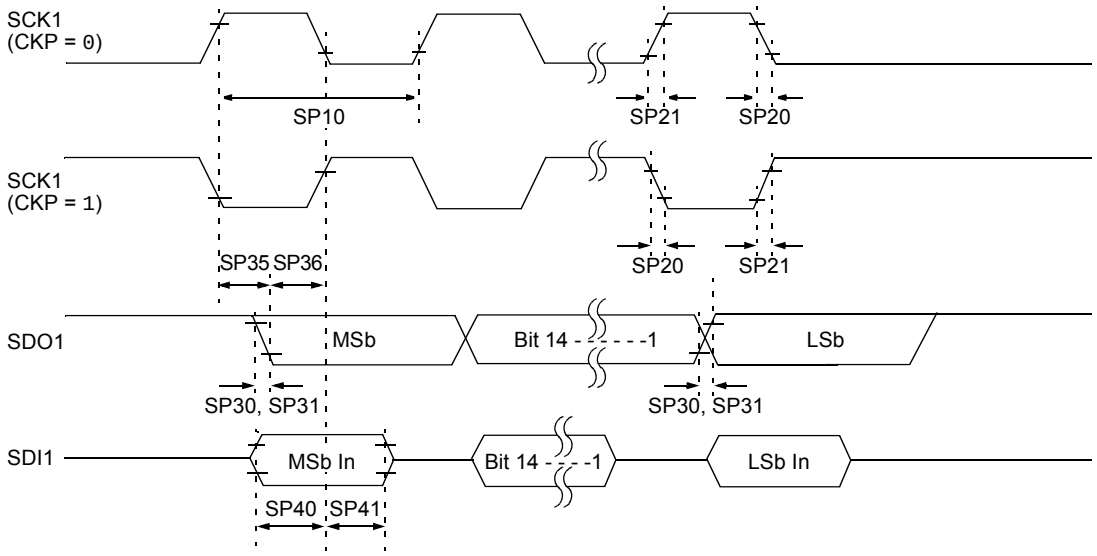
DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Parameter No.	**Typ.**	**Max.**	**Doze Ratio**	**Units**	**Conditions**		
Doze Current (I_{DOZE})(1)							
DC73a(2)	35	—	1:2	mA	-40°C	3.3V	FOSC = 140 MHz
DC73g	20	30	1:128	mA			
DC70a(2)	35	—	1:2	mA	+25°C	3.3V	FOSC = 140 MHz
DC70g	20	30	1:128	mA			
DC71a(2)	35	—	1:2	mA	+85°C	3.3V	FOSC = 140 MHz
DC71g	20	30	1:128	mA			
DC72a(2)	28	—	1:2	mA	+125°C	3.3V	FOSC = 120 MHz
DC72g	15	30	1:128	mA			

Note 1: I_{DOZE} is primarily a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all I_{DOZE} measurements are as follows:

- Oscillator is configured in EC mode and external clock is active, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{MCLR}$ = V_{DD}, WDT and FSCM are disabled
- CPU, SRAM, program memory and data memory are operational
- No peripheral modules are operating; however, every peripheral is being clocked (all PMDx bits are zeroed)
- CPU is executing `while(1)` statement
- JTAG is disabled

2: Parameter is characterized but not tested in manufacturing.

FIGURE 30-25: SPI1 MASTER MODE (FULL-DUPLEX, CKE = 0, CKP = x, SMP = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-44: SPI1 MASTER MODE (FULL-DUPLEX, CKE = 0, CKP = x, SMP = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP10	FscP	Maximum SCK1 Frequency	—	—	10	MHz	-40ºC to +125ºC **(Note 3)**
SP20	TscF	SCK1 Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP21	TscR	SCK1 Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

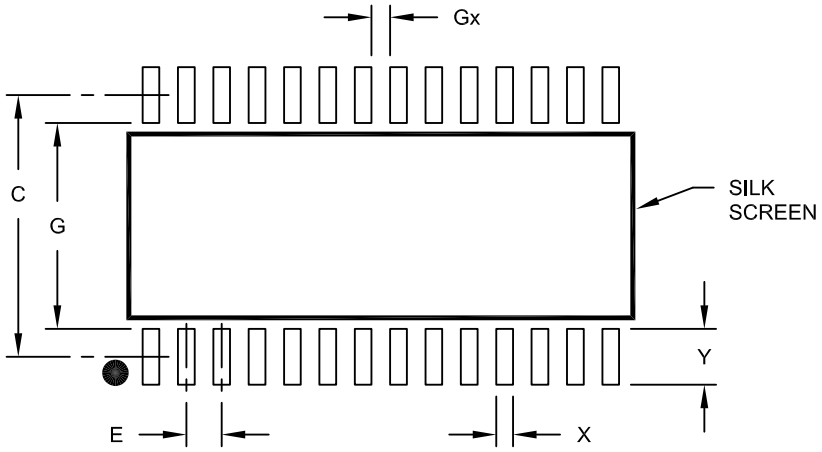
2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 100 ns. The clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		9.40	
Contact Pad Width (X28)	X			0.60
Contact Pad Length (X28)	Y			2.00
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.40		

Notes:

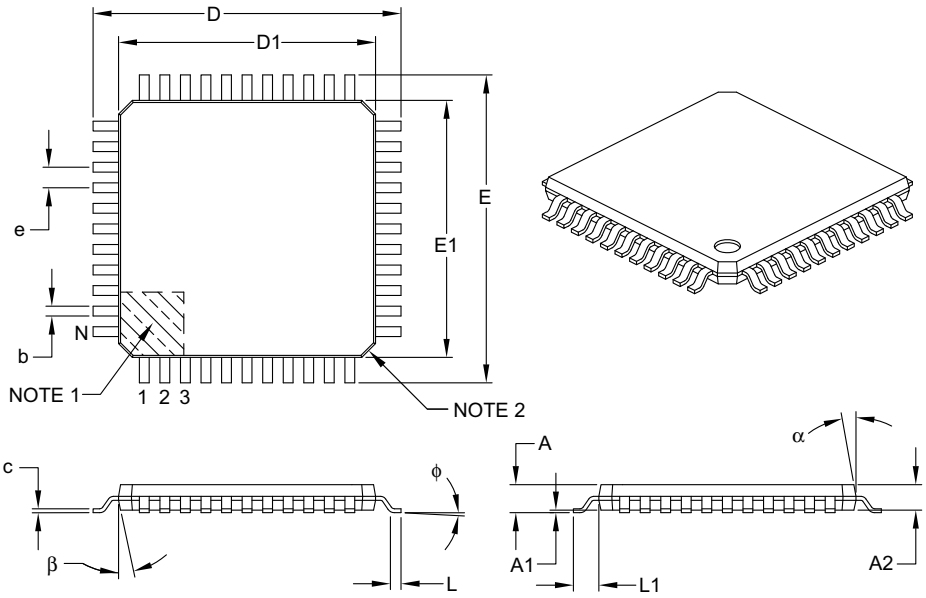
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2052A

44-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		44	
Lead Pitch	e		0.80 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		12.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.30	0.37	0.45
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-076B

TABLE A-2: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 30.0 "Electrical Characteristics" (Continued)	These SPI2 Timing Requirements were updated: • Maximum value for Parameter SP10 and the minimum clock period value for SCKx in Note 3 (see Table 30-36, Table 30-37, and Table 30-38) • Maximum value for Parameter SP70 and the minimum clock period value for SCKx in Note 3 (see Table 30-40 and Table 30-42) • The Maximum Data Rate values were updated for the SPI2 Maximum Data/Clock Rate Summary (see Table 30-43) These SPI1 Timing Requirements were updated: • Maximum value for Parameters SP10 and the minimum clock period value for SCKx in Note 3 (see Table 30-44, Table 30-45, and Table 30-46) • Maximum value for Parameters SP70 and the minimum clock period value for SCKx in Note 3 (see Table 30-47 through Table 30-50) • Minimum value for Parameters SP40 and SP41 see Table 30-44 through Table 30-50) Updated all Typical values for the CTMU Current Source Specifications (see Table 30-55). Updated Note1, the Maximum value for Parameter AD06, the Minimum value for AD07, and the Typical values for AD09 in the ADC Module Specifications (see Table 30-56). Added Note 1 to the ADC Module Specifications (12-bit Mode) (see Table 30-57). Added Note 1 to the ADC Module Specifications (10-bit Mode) (see Table 30-58). Updated the Minimum and Maximum values for Parameter AD21b in the 10-bit Mode ADC Module Specifications (see Table 30-58). Updated Note 2 in the ADC Conversion (12-bit Mode) Timing Requirements (see Table 30-59). Updated Note 1 in the ADC Conversion (10-bit Mode) Timing Requirements (see Table 30-60).